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Orcad 16.6 with PSpice

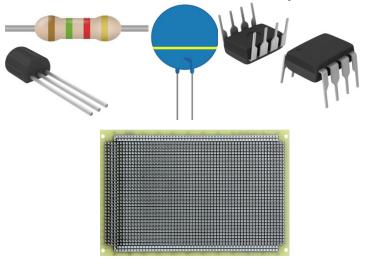
Presentation at Cadence User Conference 2016

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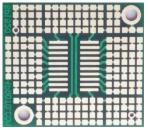


Motivation:

- Available printed boards for prototyping:
 - Wired connection components < > SMD connection components

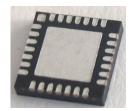






Restrictions of these solutions:

- Impossible to fulfill EMC and thermal considerations
- Impossible to use individual component footprints

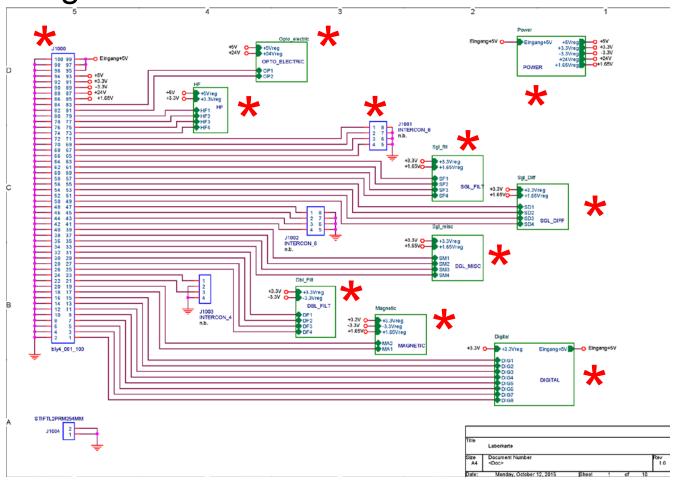


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6 Layers are the minimum for fulfilling all EMC:

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	🛂 Lay	out Cross	Section	L						_	-		- 🗆 X
llr													
		Subclass Name	Туре		Material		Thickness (MM)	Conductivity (mho/cm)	Dielectric Constant	Loss Tangent	Negative Artwork	Shield	
	1		SURFACE		AIR				1	0			
	2	TOP	CONDUCTOR	•	COPPER	•	0.03	595900	4.5	0			
	3		DIELECTRIC	-	FR-4	•	0.1	0	4.5	0.035			
	4	GND	PLANE	-	COPPER	•	0.03	595900	4.5	0.035		×	
	5		DIELECTRIC	-	FR-4	•	0.1	0	4.5	0.035	_	_	
	6	VCC	PLANE	-	COPPER	•	0.03	595900	4.5	0.035		×	
	7	VCC2	DIELECTRIC PLANE	• •	FR-4 COPPER	• •	0.42	0 595900	4.5 4.5	0.035		×	
	9	VULZ	DIELECTRIC	• •	FR-4	•	0.03	00000	4.5	0.035			
	10	GND2	PLANE	• •	COPPER	•	0.03	595900	4.5	0.035		×	
	11	unt/2	DIELECTRIC	-	FR-4	+	0.03	00000	4.5	0.035			
	12	BOTTOM	CONDUCTOR	•	COPPER	+	0.03	595900	4.5	0			
	13		SURFACE		AIR				1	0			
	•												
Total Thickness: Layer Type Material Field to Set Value to Set 1 MM ALL Thickness Update Fields													
OK Apply Cancel Refresh Materials ->													

Blockdiagram:



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Top layer and ground (layer 2 and 5)

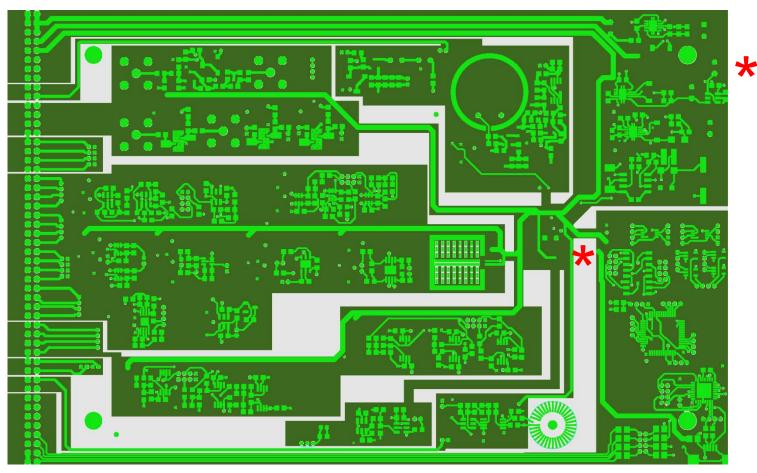
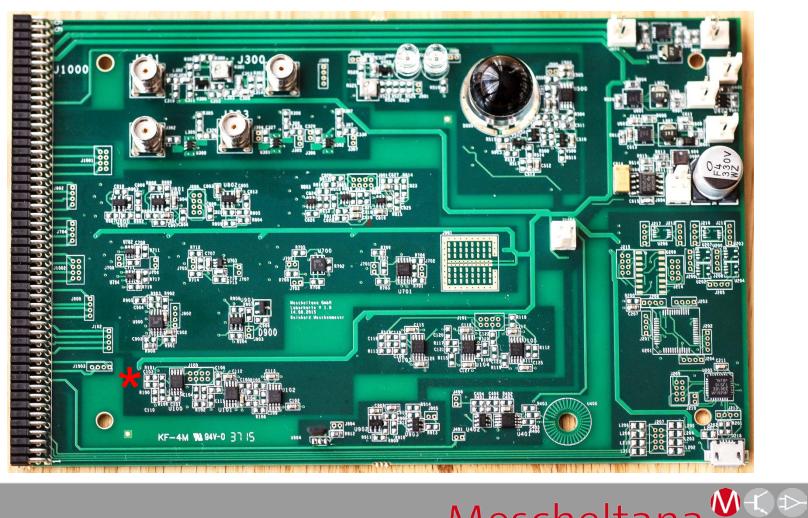
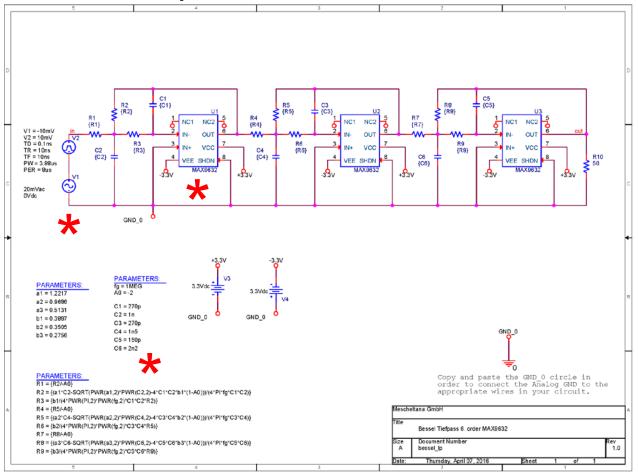


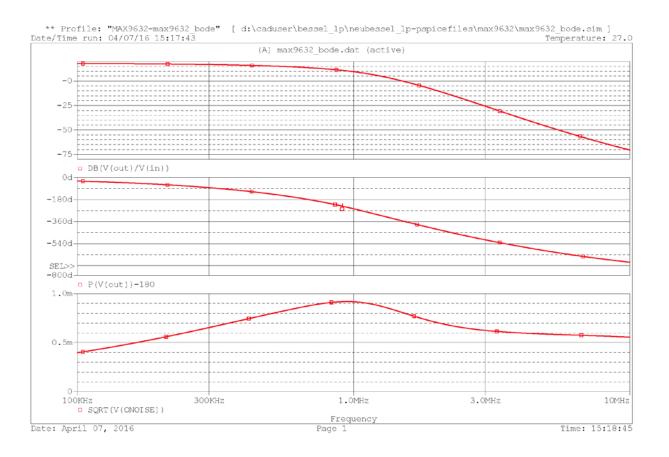
Photo of the partly mounted board:



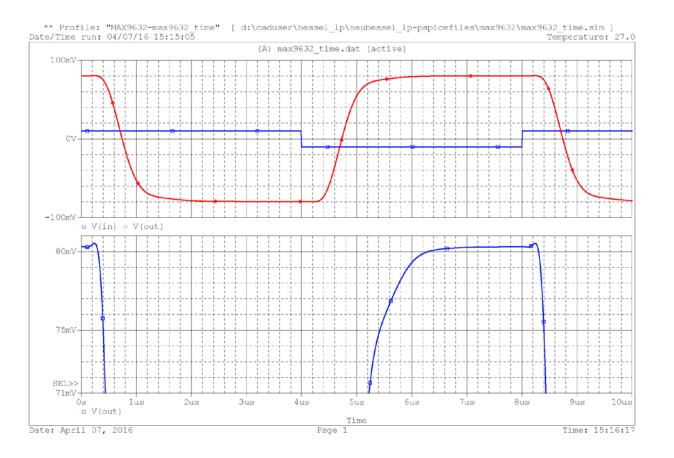
Circuit of the PSpice simulation:



Frequency simulation:



Time simulation:



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Finally:

- → My offer to customers:
 - Sale of the unmounted board
 - Sale a partly mounted version of the board
 - Individual configuration to customer requirements
 - Use of parts and concepts as a base for individual developments
- → Evaluation the whole schematics:

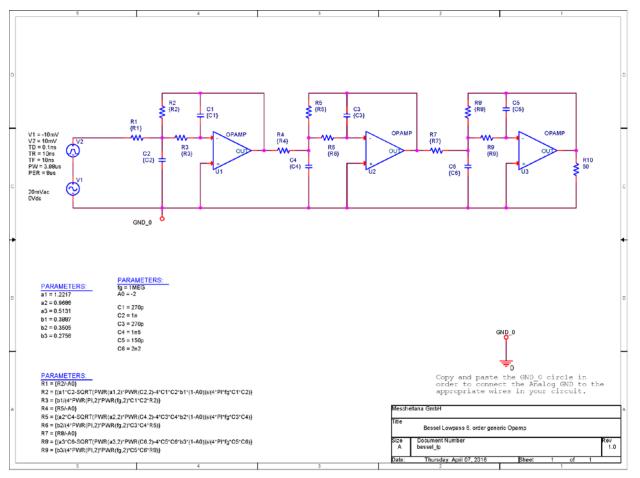
http://www.mescheltana.de/LABORKARTE3_link.pdf

- → Reference:
 - [1] Tietze, U., Schenk, C., & Gamm, E. (2009). Halbleiter-Schaltungstechnik. Erlangen und München: Springer.

Questions?

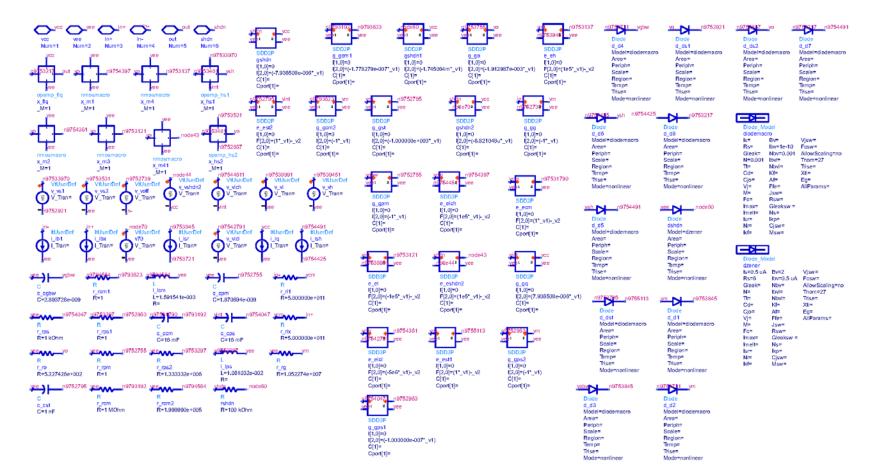
→Backup

Simulation with generic operational amplifier:



Mescheltana MCD

Spice model of the max9632:



Excel calculation of the components:

Bessel Filter 6th Order from Tietze-Schenk:

a1= a2= a3=	1,2217 0,9686 0,5131			
b1=	0,3887			
b2=	0,3505			
b3=	0,2756			
fg= A0=	1,00E+06 -2	wg= 1,26E+07		
C1=	2,70E-10		zC1=	294,73
C2=	1,00E-09	C2ref= 8,44E-10	zC2=	79,58
C3=	2,70E-10		zC3=	294,73
C4=	1,50E-09	C4ref= 1,21E-09	zC4=	53,05
C5=	1,00E-10		zC5=	795,77
C6=	1,50E-09	C6ref= 1,26E-09	zC6=	53,05
R1=	108,88			
R2=	217,76			
R3=	56,45			
R4=	112,89			
R5=	121,85			
R6=	243,70			